



Advanced Schottky Barrier Diodes

ASD723SN

Features:

- Designed for mounting on small surface
- Low stored charge
- Majority carrier conduction

Mechanical data:

- Case: 0805(2012) Standard package, molded plastic
- Terminals : Solder plated, solderable per MIL-STD-750, method 2026.
- Polarity: Indicated by cathode band
- Mounting position: Any
- Weight: 4.8mg (approximately)

Absolute Maximum Ratings(Ta=25°C)

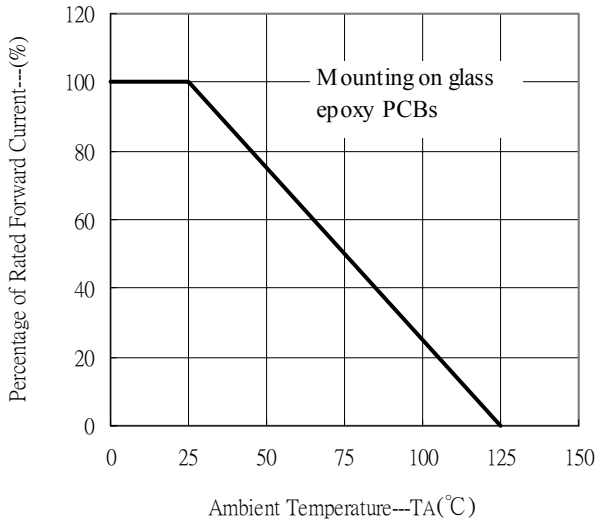
Characteristics	Symbol	Value	Unit
Continuous Reverse Voltage	V _R	30	V
Average Rectified Current	I _O	200	mA
Forward Surge Current @ 8.3ms single half sine-wave superimposed on rated load(JEDEC method)	I _{FSM}	1.5	A
Capacitance between Terminals @ f=1MHz and applied 10VDC Reverse Voltage	C _T	20	pF
Junction Temperature	T _j	-40 to +125	°C
Storage Temperature Range	T _{stg}	-40 to +125	°C

Electrical Characteristics (T_A=25°C, unless otherwise noted)

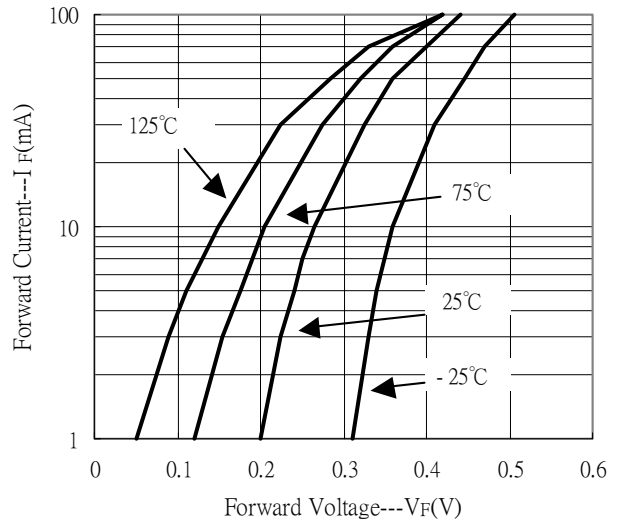
Parameter	Condition	Symbol	Min	Typ	Max	Unit
Forward Voltage	I _F = 200mA DC	V _F	-	-	0.55	V
Reverse Current	V _R = 30VDC	I _R	-	-	15	μA

Characteristic Curves

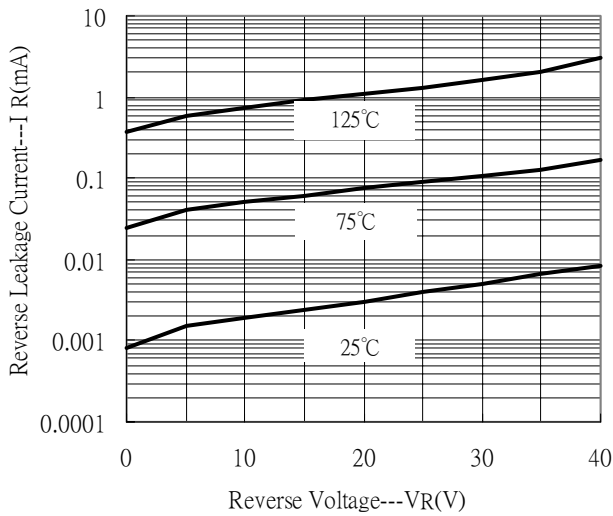
Forward Current Derating Curve



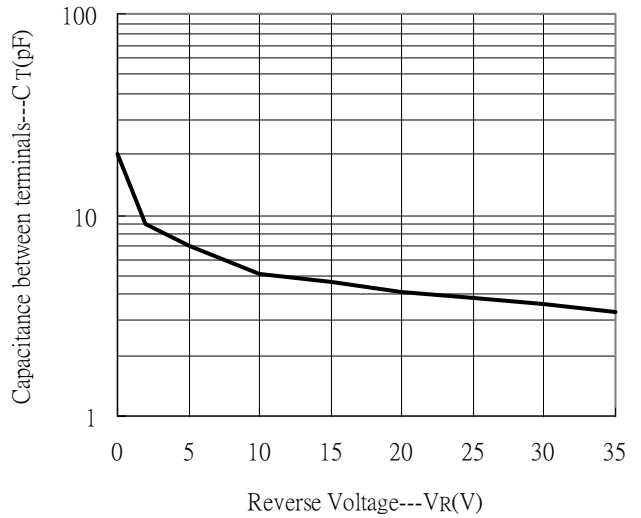
Forward Current vs Forward Voltage



Reverse Leakage Current vs Reverse Voltage



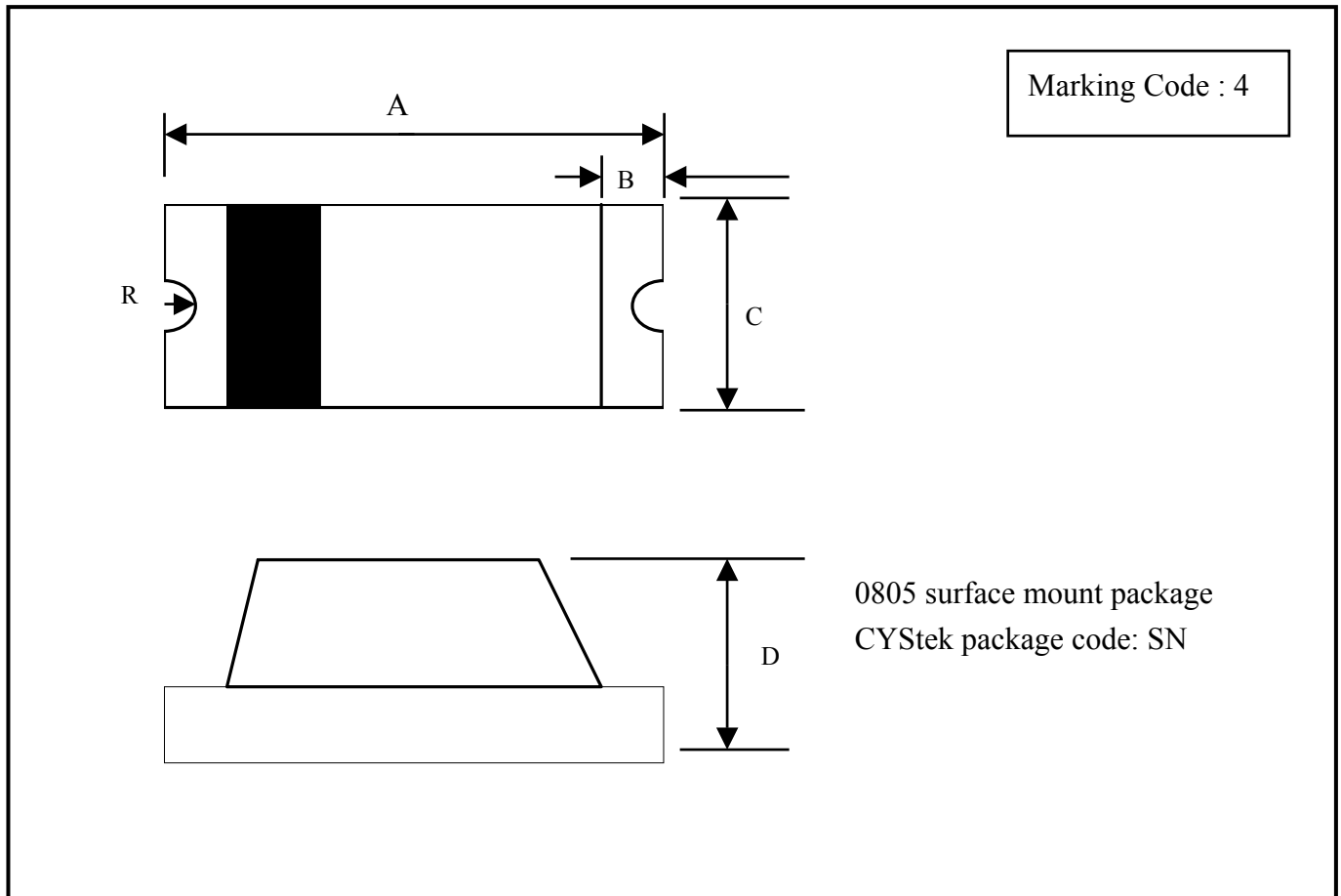
Capacitance vs Reverse Voltage



Packing Information

Case No.		0805	
Taping	Dimensions	<p>Material : Plastics</p>	
	Quantity	Standard capacity : 3,000pcs / reel	
Reel	Dimensions	<p>Material : Card board</p>	
	Leader and Trailer		
Standard Package	Dimensions	CARTON <p>Material : Corrugated card board</p>	INNER BOX <p>Material : Corrugated card board</p>
	Quantity	Standard capacity : 150,000pcs / carton (50 reels / carton)	Standard capacity : 15,000pcs / box (5 reels / box)

0805(2012) Dimension



*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.079	0.087	2.00	2.20	C	0.047	0.055	1.20	1.40
B	0.016(typ.)		0.40(typ.)		D	0.035	0.043	0.90	1.10
R	0.008(tup.)		0.20(typ.)						

Notes : 1.Controlling dimension : millimeters.
 2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

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